

PRODUCT SPECIFICATION

11.45" TFT LCD MODULE MODEL: T115128720-A0WMN-001 Ver:1.1

< >> Preliminary Specification

< >> Finally Specification

CUSTOMER'S APPROVAL						
CUSTOMER:	CUSTOMER:					
SIGN	ATURE:	DATE:				

APPROVED	PM	PD	PREPARED
BY	REVIEWED	REVIEWED	BY

Revision History

Revision	Date	Originator	Detail	Remarks
Ver 1.0	2016.08.31	ZFY	Initial Release	
1.1	2018.04.12	ZFY	Modify many details	P22/P23

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1. General Description

The specification is a transmissive type color active matrix liquid crystal display (LCD) which uses amorphous thin film transistor (TFT) as switching devices. This product is composed of a TFT-LCD panel, driver ICs and a backlight unit.

2. Module Parameter

Features	Details	Unit
Display Size(Diagonal)	11.45"	
Display Mode	Transmissive /Normally black	
Resolution	1280 RGB x 720	Pixels
View Direction	FULL View	Best Image
Module Outline	268(H) x 162.5(V) x 5.7(T) (Note1)	mm
Active Area	253.44(H) x142.56(V)	mm
Pixel Pitch	198(H) x 198(V)	um
Pixel Arrangement	RGB 2domain stripe	
Display Colors	16.7M	
Interface	LVDS Interface	
Driver IC	HX8292-A & HX8695-E	
With or without the touch panel	Without	
Operating Temperature	-20∼70	°C
Storage Temperature	-40~85	°C
Weight	(444)	g

Note 1: Inclusive hooks, posts, FFC/FPC tail etc.

3. Absolute Maximum Ratings

V_{SS}=0V, Ta=25°C

Item	Symbol	Min.	Max.	Unit
Digital Supply Voltage	VCC	-0.1	3.96	V
Storage temperature	T _{STG}	-40	85	°C
Operating temperature	T _{OP}	-20	70	°C

Note 1: If Ta below 50°C, the maximal humidity is 90%RH, if Ta over 50°C, absolute humidity should be less than 60%RH.

Note 2: The response time will be extremely slow when the operating temperature is around -10 $^{\circ}$ C, and the back ground will become darker at high temperature operating.

4. DC Characteristics

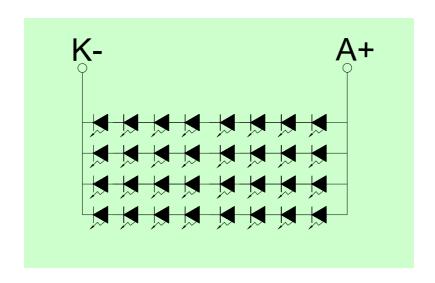
Item	Symbol	Min.	Тур.	Max.	Unit	
		VDD	3	3.3	3.6	V
Cupply Voltage			11.5	11.55	11.6	V
Supply voltage	Supply Voltage		16.9	18	19	V
		VGL	-8	-9	-10	V
Differential input high threshold voltage		VLVTH	100	-	300	mV
Differential input low threshold voltage		VLVTL	-300	-	-100	mV
urrent Consumption All White	Logic Analog	ICC+ IIN	-	42	90	mA

5. Backlight Characteristic

5.1. Backlight Characteristic

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Forward Voltage	VF	Ta=25 °C, I _F =60mA/LED	22.4	25.6	27.2	V
Forward Current	lF	Ta=25 °C, V _F =3.2V/LED		240		mA
Power dissipation	Pb	-		6.15		W
Uniformity	Avg	-	70	-	-	%
Drive method	Constant current					
LED Configuration	32	White LEDs (8 LEDs in one strin	g and 4 g	groups in	n paralle	1)

5.2. Backlighting circuit



6. Optical Characteristics

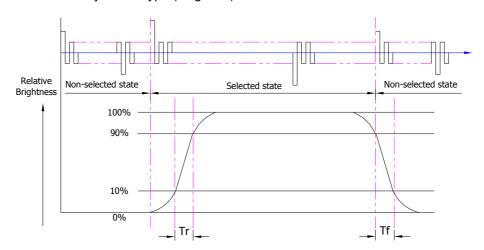
6.1. Optical Characteristics

Ta=25°C, V_{DD} =3.3V, TN LC+ Polarizer

	lto	ltem		Condition	S	pecificati	on	Unit
	item		Symbol	Condition	Min.	Тур.	Max.	Unit
	Luminar	nce on						
(a)	$TFT(I_f = 60)$)mA/LED)	Lv		450	550	-	cd/m²
ppo	Contrast rati	o(See 6.3)	CR		700	900	-	
Backlight On (Transmissive Mode)	Response time (See 6.2)		TR+TF		-	30	40	ms
nis		Red	XR		0.597	0.647	0.697	
nsr	Chromoticity	1760	YR		0.288	0.338	0.388	
Tra		Chromaticity Green Transmissive (See 6.5) Blue	XG		0.271	0.321	0.371	
n (•		YG		0.568	0.618	0.668	
ht 0	(See 6.5)		Хв		0.097	0.147	0.197	
	(000 0.0)	Diue	Yв		0.034	0.084	0.134	
ack		White	Xw		0.263	0.313	0.363	
B		VVIIIC	Yw		0.279	0.329	0.379	
	Viewing	Horizontal	θx+		-	80	-	
	Angle	Tionzontal	θх-	Center CR≥10	-	80	-	Deg.
	(See 6.4)	Vertical	φY+		-	80	-	Dog.
	(555 6.4)	vertical	φY-		-	80	-	
	NTSC ra	tio(Color gar	mut)		65	70	-	%

6.2. Definition of Response Time

6.2.1. Normally Black Type (Negative)



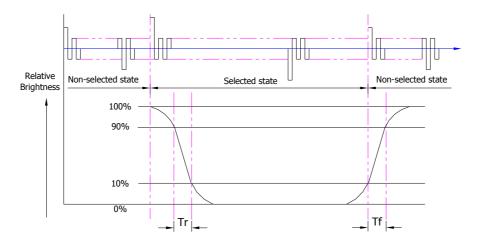
Tr is the time it takes to change form non-selected stage with relative luminance 10% to selected state with relative luminance 90%;

Tf is the time it takes to change from selected state with relative luminance 90% to

non-selected state with relative luminance 10%.

Note: Measuring machine: LCD-5100

6.2.2. Normally White Type (Positive)



Tr is the time it takes to change form non-selected stage with relative luminance 90% to selected state with relative luminance 10%;

Tf is the time it takes to change from selected state with relative luminance 10% to non-selected state with relative luminance 90%;

Note: Measuring machine: LCD-5100 or EQUI

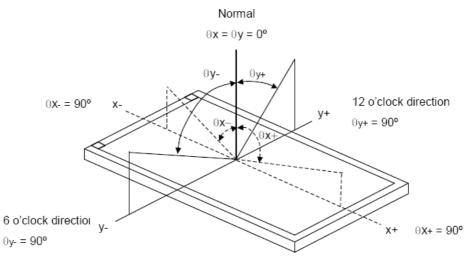
6.3. Definition of Contrast Ratio

Contrast is measured perpendicular to display surface in reflective and transmissive mode. The measurement condition is:

Measuring Equipment	Eldim or Equivalent	
Measuring Point Diameter	3mm//1mm	
Measuring Point Location	Active Area centre point	
Toot pottorn	A: All Pixels white	
Test pattern	B: All Pixel black	
Contrast setting	Maximum	

Definitions: CR (Contrast) = Luminance of White Pixel / Luminance of Black Pixel

6.4. Definition of Viewing Angles

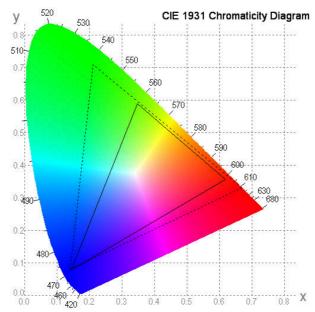


Measuring machine: LCD-5100 or EQUI

6.5. Definition of Color Appearance

R,G,B and W are defined by (x, y) on the IE chromaticity diagram NTSC=area of RGB triangle/area of NTSC triangleX100%

Measuring picture: Red, Green, Blue and White (Measuring machine: BM-7)

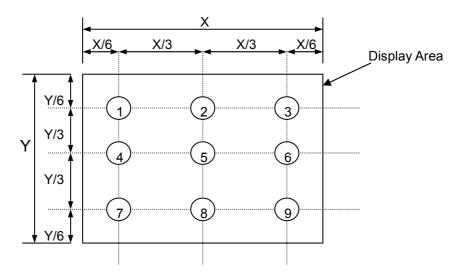


6.6. Definition of Surface Luminance, Uniformity and Transmittance

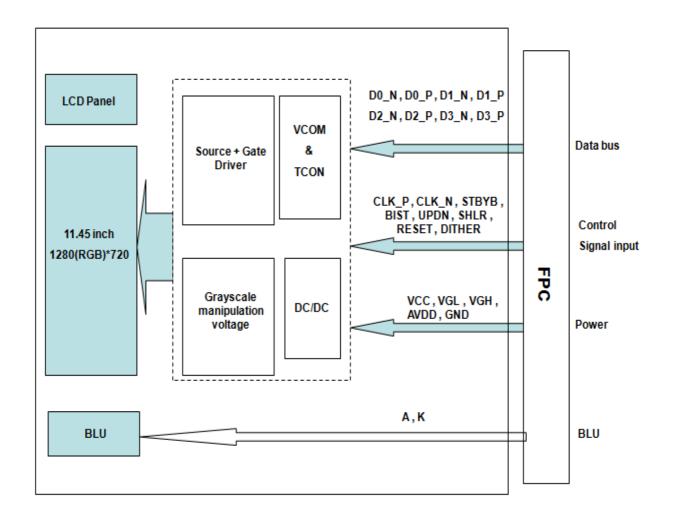
Using the transmissive mode measurement approach, measure the white screen luminance of the display panel and backlight.

- 6.6.1. Surface Luminance: L_V = average (L_{P1} : L_{P9})
- 6.6.2. Uniformity = Minimal $(L_{P1}:L_{P9})$ / Maximal $(L_{P1}:L_{P9})$ * 100%
- 6.6.3. Transmittance = L_V on LCD / L_V on Backlight * 100%

Note: Measuring machine: BM-7



7. Block Diagram and Power Supply



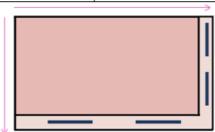
8. Interface Pins Definition

No.	Symbol	Function	Remark
1	VCC	Power supply (3.3V)	
2	VCC	Power supply (3.3V)	
3	NC	Not connected	
4	GND	Ground	
5	GND	Ground	
6	NC	Not connected	
7	NC	Not connected	
8	UPDN	Up/Down scan control	Note1
9	SHLR	Left/Right shift control	Note1
10	RESET	Global Reset	Note2
11	STBYB	Standby mode control	Note3
12	BIST	BIST enable	Note4
13	GND	Ground	
14	NC	Not connected	
15	VGL	Gate off voltage	
16	VGL	Gate off voltage	
17	VGH	Gate on voltage	
18	VGH	Gate on voltage	
19	AVDD	Analog power	
20	AVDD	Analog power	
21	NC	Not connected	
22	GND	Ground	
23	GND	Ground	
24	CLK_N	LVDS clock-	
25	CLK_P	LVDS clock+	
26	GND	Ground	
27	D0_N	LVDS data 0-	
28	D0_P	LVDS data 0+	
29	GND	Ground	
30	D1_N	LVDS data 1-	
31	D1_P	LVDS data 1+	
32	GND	Ground	
33	D2_N	LVDS data 2-	
34	D2_P	LVDS data 2+	
35	GND	Ground	
36	D3_N	LVDS data 3-	
37	D3_P	LVDS data 3+	
38	GND	Ground	
39	GND	Ground	
40	SCL	SPI interface clock	Note5
41	SDA	SPI interface data	Note5

42	CS	SPI chip select	Note5
43	GND	Ground	
44	DITHER	Dithering setting	Note6
45	AVDD	Analog power	
46	AVDD	Analog power	
47	NC	Not connected	
48	NC	Not connected	
49	NC	Not connected	
50	NC	Not connected	

Note1

Scan Contr	ol Input	Scanning direction
SHLR	UPDN	
High	High	Left to Right, Up to Down (Default)
High	Low	Left to Right, Down to Up
Low	High	Right to Left, Up to Down
Low	Low	Right to Left, Down to Up



Note 2

Global Reset, keep VDD during operation.

Suggest to connect with RC reset circuit stability. Normally pull high.

Note 3

STBYB = "H(3.3V)" normal operation (default);

STBYB = "L(GND)" timing control, source driver will turn off, all output are High -Z;

Note 4

BIST= "H(3.3V)" BIST mode(CLK input is not needed);

BIST = "L(GND)" normal operation (default);

Note 5

SPI interface is only for LCD internal tunning, please keep them NC (Not Connection).

Note 6

DITHER= "H(3.3V)" Enable internal dithering function(default);

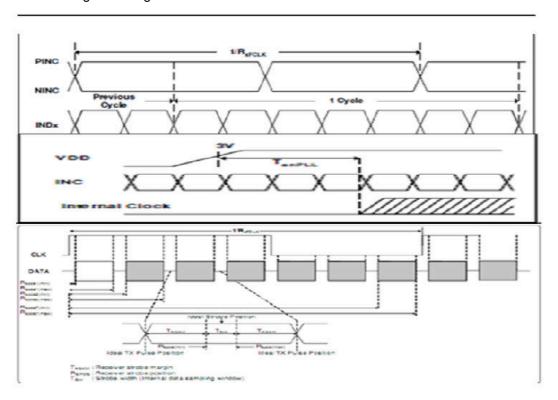
DITHER = "L(GND)" Disenable internal dithering function;

9. LVDS SIGNAL SPECIFICATION

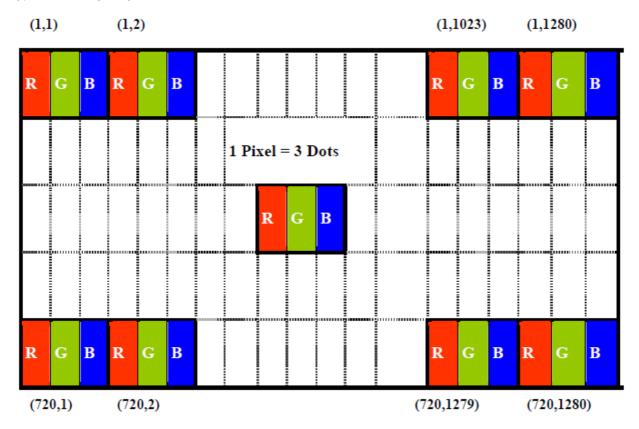
1) LVDS Signal Electrical Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Clock frequency	RxFCLK	60	65.5	71.3	MHz	
Horizontal Display Area	thd		1280		DCLK	
HS Period	th	1370	1440	1500	DCLK	
HS Blanking	Thb+thfp	90	160	220	DCLK	
Vertical Display Area	tvd		720		TH	
VS Period	tv	730	758	792	TH	
VS Blanking	Tvbp+tvfp	10	38	72	TH	
Input data skew margin	TRSKM	500	-	-	ps	VIID =400m V RxVCM=1.2 V RxFCLK=65. 5MHz
Clock high time	TLVCH	-	4/ (7*RxFCLK)		ns	
Clock low time	TLVCL		3/ (7*RxFCLK)		ns	
PLL wake-up time	TenPLL			150	us	

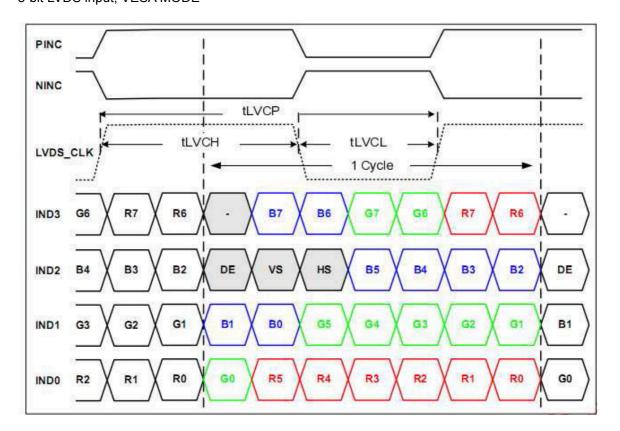
2) LVDS Signal Timing



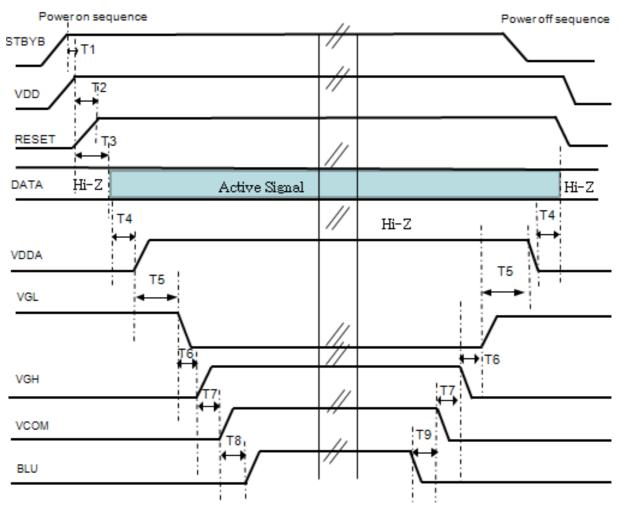
3) DATA INPUT FORMAT



4) LVDS Input Signal Format8-bit LVDS input, VESA MODE



5) POWER ON/OFF SEQUENCE



Parameter	Cb-al	Timing			Unit	Notes
	Symbol	Min	Typ.	Max	Unit	Notes
	T1	2	-	-		
	T2	0.5	-	-	ms	
	T3	20	-	-		
	T4	5	-	-		
Power On & Off sequence	T5	5	-	-		
	Т6	5	-	-		
	T 7	5	-	-		
	T8	200	-	-		
	Т9	500		-		

10. Quality Assurance

10.1 Purpose

This standard for Quality Assurance assures the quality of LCD module products supplied to customer.

10.2 Standard for Quality Test

10.2.1 Sampling Plan:

GB2828.1-2012

Single sampling, general inspection level II

10.2.2 Sampling Criteria:

Visual inspection: AQL 1.5% Electrical functional: AQL 0.65%.

10.2.3 Reliability Test:

Detailed requirement refer to Reliability Test Specification.

10.3 Nonconforming Analysis & Disposition

- 10.3.1 Nonconforming analysis:
 - 10.3.1.1 Customer should provide overall information of non-conforming sample for their complaints.
 - 10.3.1.2 After receipt of detailed information from customer, the analysis of nonconforming parts usually should be finished in one week.
 - 10.3.1.3 If cannot finish the analysis on time, customer will be notified with the progress status.
- 10.3.2 Disposition of nonconforming:
 - 10.3.2.1 Non-conforming product over PPM level will be replaced.
 - 10.3.2.2 The cause of non-conformance will be analyzed. Corrective action will be discussed and implemented.

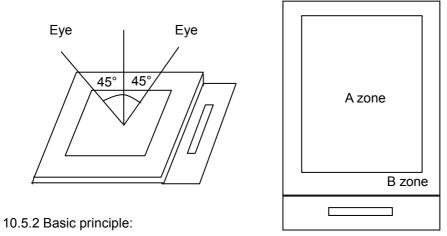
10.4 Agreement Items

Shall negotiate with customer if the following situation occurs:

- 10.4.1 There is any discrepancy in standard of quality assurance.
- 10.4.2 Additional requirement to be added in product specification.
- 10.4.3 Any other special problem.

10.5 Standard of the Product Visual Inspection

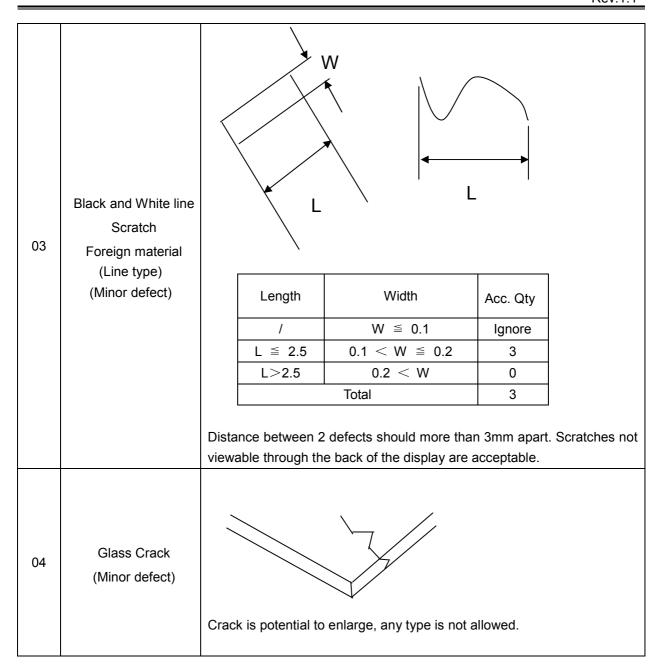
- 10.5.1 Appearance inspection:
 - 10.5.1.1 The inspection must be under illumination about 1000 1500 lx, and the distance of view must be at 30cm ± 2cm.
 - 10.5.1.2 The viewing angle should be 45° from the vertical line without reflection light or follows customer's viewing angle specifications.
 - 10.5.1.3 Definition of area: A Zone: Active Area, B Zone: Viewing Area,

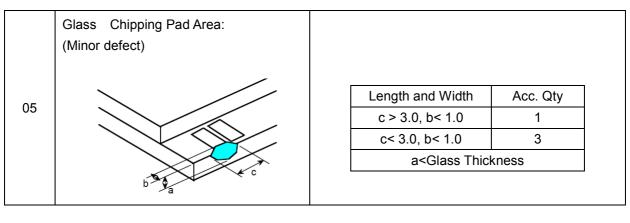


- 10.5.2.1 A set of sample to indicate the limit of acceptable quality level must be discussed by both us and customer when there is any dispute happened.
- 10.5.2.2 New item must be added on time when it is necessary.

10.6 Inspection Specification

No.	Item	Criteria (Unit: mm)			
01	Black / White spot Foreign material (Round type) Pinholes Stain Particles inside cell. (Minor defect)	φ= (a + b)/2 Distance between 2 defects s	Size	0 lg 0.50 l	nc. Qty gnore N≤3 0
02	Electrical Defect (Minor defect)	Bright dot Dark dot Total dot	Total N ≤ 2 N ≤ 4 N ≤ 4 ough 5% ND rs.	Note 1 Note 2	





	Glass Chipping Rear of Pad Area: (Minor defect)		
	,	Length and Width	Acc. Qty
		c > 3.0, b< 1.0	1
06		c< 3.0, b< 1.0	2
		c< 3.0, b< 0.5	4
		a <glass td="" thic<=""><td>kness</td></glass>	kness
	b a		
	Glass Chipping Except Pad Area: (Minor defect)		
		Length and Width	Acc. Qty
		c > 3.0, b< 1.0	1
07		c< 3.0, b< 1.0	2
		c< 3.0, b< 0.5	4
		a <glass td="" thic<=""><td>kness</td></glass>	kness
	a		
	Glass Corner Chipping: (Minor defect)	<u>-</u>	
		Length and Width	Acc. Qty
		c < 3.0, b< 3.0	Ignore
08		a <glass td="" thic<=""><td>kness</td></glass>	kness
	ba		
	Glass Burr:		
	(Minor defect)		
		Length	Acc. Qty
09	F	F < 1.0	Ignore
		1 - 1.0	19.1010
	F	Glass burr don't affect as dimension.	semble and module

10	FPC Defect: (Minor defect) a w a	- ←	10.1 Dent, pinhole (w: circuitry width.) 10.2 Open circuit is 10.3 No oxidation,	s unacceptable.	nd distortion.
11	Bubble on Polarizer (Minor defect)		Diameter φ≤0.30 0.30 <φ≤0.50 0.50 < φ	Acc. Qty Ignore N≤2 N=0	
12	Dent on Polarizer (Minor defect)		Diameter φ≤0.25 0.25 <φ≤0.50 0.50 < φ	Acc. Qty Ignore N≤4 None	
13	Bezel		tortion on the Bezel. ingerprints, stains or oth	er contamination	1.
14	Touch Panel	D: Diameter W: width L: length 14.1 Spot: D<0.25 is acceptable 0.25 ≤ D ≤ 0.4 2dots are acceptable and the distance between defects should more than 10 mm. D>0.4 is unacceptable 14.2 Dent: D>0.40 is unacceptable 14.3 Scratch: W≤0.03, L≤10 is acceptable, 0.03 <w≤0.10, 10="" 2="" acceptable="" between="" defects="" distance="" is="" l≤10="" mm.="" more="" should="" than="" w="">0.10 is unacceptable.</w≤0.10,>			should more than
15	PCB	15.1 No distortion or contamination on PCB terminals. 15.2 All components on PCB must same as documented on the BOM/component layout. 15.3 Follow IPC-A-600F.			

16	Soldering	Follow IPC-A-610C standard
17	Electrical Defect (Major defect)	The below defects must be rejected. 17.1 Missing vertical / horizontal segment, 17.2 Abnormal Display. 17.3 No function or no display. 17.4 Current exceeds product specifications. 17.5 LCD viewing angle defect. 17.6 No Backlight. 17.7 Dark Backlight. 17.8 Touch Panel no function.

Remark: LCD Panel Broken shall be rejected. Defect out of LCD viewing area is acceptable.

10.7 Classification of Defects

- 10.7.1 Visual defects (Except no / wrong label) are treated as minor defect and electrical defect is major.
- 10.7.2 Two minor defects are equal to one major in lot sampling inspection.

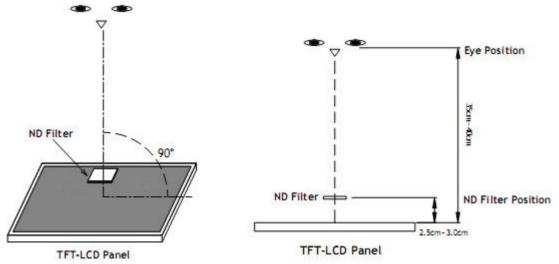
10.8 Identification/marking criteria

Any unit with illegible / wrong /double or no marking/ label shall be rejected.

10.9 Packaging

- 10.9.1 There should be no damage of the outside carton box, each packaging box should have one identical label.
- 10.9.2 Modules inside package box should have compliant mark.
- 10.9.3 All direct package materials shall offer ESD protection

Note1: Bright dot is defined as the defective area of the dot is larger than 50% of one sub-pixel area.



Bright dot: The bright dot size defect at black display pattern. It can be recognized by 2% transparency of filter when the distance between eyes and panel is $350 \text{mm} \pm 50 \text{mm}$.

Dark dot: Cyan, Magenta or Yellow dot size defect at white display pattern. It can be recognized by 5% transparency of filter when the distance between eyes and panel is $350 \text{mm} \pm 50 \text{mm}$.

Note2: Mura on display which appears darker / brighter against background brightness on parts of display area.

11. Reliability Specification

No	ltem	Condition	Quantity	Criteria
1	High Temperature Operating	70℃, 96Hrs	2	GB/T2423.2 -2008
2	Low Temperature Operating	-20℃, 96Hrs	2	GB/T2423.1 -2008
3	High Humidity	50℃, 90%RH, 96Hrs	2	GB/T2423.3 -2006
4	High Temperature Storage	85℃, 96Hrs	2	GB/T2423.2 -2008
5	Low Temperature Storage	-40℃, 96Hrs	2	GB/T2423.1 -2008
6	Thermal Cycling Test	-20℃, 60min~70℃, 60min, 20 cycles.	2	GB/T2423.22 -2012
7	Packing vibration	Frequency range:10Hz~50Hz Acceleration of gravity:5G X,Y,Z 30 min for each direction.	2	GB/T5170.14 -2009
8	Floatrical Static Discharge	Air: \pm 8KV 150pF/330 Ω 5 times	2	GB/T17626.2 -2006
0	Electrical Static Discharge	Contact: \pm 4KV 150pF/330 Ω 5 times		
9	Drop Test (Packaged)	Height:80 cm,1 corner, 3 edges, 6 surfaces.	2	GB/T2423.8 -1995

Note1. No defection cosmetic and operational function allowable.

Note2. Total current Consumption should be below double of initial value

12. Precautions and Warranty

12.1. Safety

12.1.1 The liquid crystal in the LCD is poisonous. Do not put it in your mouth. If the liquid crystal touches your skin or clothes, wash it off immediately using soap and water.

12.1.2 Since the liquid crystal cells are made of glass, do not apply strong impact on them. Handle with care.

12.2. Handling

12.2.1 Reverse and use within ratings in order to keep performance and prevent damage.

12.2.2 Do not wipe the polarizer with dry cloth, as it might cause scratch. If the surface of the LCD needs to be cleaned, wipe it swiftly with cotton or other soft cloth soaked with petroleum IPA, do not use other chemicals.

12.3.Storage

12.3.1. Do not store the LCD module beyond the specified temperature ranges.

12.3.2. Strong light exposure causes degradation of polarizer and color filter

12.4. Metal Pin (Apply to Products with Metal Pins)

12.4.1 Pins of LCD and Backlight

12.4.1.1 Solder tip can touch and press on the tip of Pin LEAD during the soldering

12.4.1.2 Recommended Soldering Conditions

Solder Type: Sn96.3~94-Ag3.3~4.3-Cu0.4~1.1

Maximum Solder Temperature: 370 ℃

Maximum Solder Time: 3s at the maximum temperature

Recommended Soldering Temp: 350±20 ℃

Typical Soldering Time: ≤3s

12.4.1.3 Solder Wetting

Solder Pin Lead
Recommended

Solder Pin Lead

Not Recommended

12.4.2Pins of EL

12.4.2.1 Solder tip can touch and press on the tip of EL leads during soldering.

12.4.2.2 No Solder Paste on the soldering pad on the motherboard is recommended.

12.4.2.3 Recommended Soldering Conditions

Solder type: Nippon Alimit Leadfree SR-34, size 0.5mm

Recommended Solder Temperature: 270~290 ℃

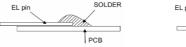
Typical Soldering Time: ≤2s

Minimum solder distance from EL lamp (body):2.0mm

12.4.2.4 No horizontal press on the EL leads during soldering.

12.4.2.5 180° bend EL leads three times is not allowed.

12.4.2.6 Solder Wetting



SOLDER

Recommended

Not Recommended

12.4.2.7 The type of the solder iron:





Recommended

Not Recommended

12.4.2.8 Solder Pad



12.5. Operation

- 12.5.1. Do not drive LCD with DC voltage
- 12.5.2. Response time will increase below lower temperature
- 12.5.3. Display may change color with different temperature
- 12.5.4. Mechanical disturbance during operation, such as pressing on the display area, may cause the segments to appear "fractured".
- 12.5.5. Do not connect or disconnect the LCM to or from the system when power is on.
- 12.5.6. Never use the LCM under abnormal condition of high temperature and high humidity.
- 12.5.7. Module has high frequency circuits. Sufficient suppression to the electromagnetic interface shall be done by system manufacturers. Grounding and shielding methods may be important to minimize the interference.
- 12.5.8. Do not display the fixed pattern for long time (we suggest the time not longer than one hour) because it may develop image sticking due to the TFT structure.

12.5 Static Electricity

- 12.5.1 CMOS LSIs are equipped in this unit, so care must be taken to avoid the electro-static charge, by ground human body, etc.
- 12.5.2 The normal static prevention measures should be observed for work clothes and benches.
- 12.5.3 The module should be kept into anti-static bags or other containers resistant to static for storage.

12.6 Limited Warranty

- 12.7.1 Our warranty liability is limited to repair and/or replacement. We will not be responsible for any consequential loss.
- 12.7.2 If possible, we suggest customer to use up all modules in six months. If the module storage time over twelve months, we suggest that recheck it before the module be used.
- 12.7.3 After the product shipped, any product quality issues must be feedback within three months, otherwise, we will not be responsible for the subsequent or consequential events.

13. Packaging

TBD

